



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Kuniko Kikuta

Serial No.: 09/584,739

Group Art Unit: 2814

Filed: June 1, 2000

Examiner: Quach, Tuan N.

For: COPPER-ALLOY INTERCONNECTION LAYER

Honorable Commissioner of Patents
Washington, D.C. 20231
BOX AF

AF

GP2814
10/B(N-E)
T. Steptoe
9-24-02

M. Brunson
10/25/02

AMENDMENT UNDER 37 C.F.R. §1.116

Sir:

In response to the Office Action dated **July 2, 2002**, please amend the above-identified application as follows:

IN THE CLAIMS:

Please amend the following claims:

1. (Amended) An electrically conductive layer comprising:
a copper alloy which includes at least one of Bi, Sb, and Ti at not less than 0.1 percent
by weight,
wherein said copper alloy has a melting point less than copper.

22. (Amended) A semiconductor device comprising:
a semiconductor substrate;
an insulation layer over said semiconductor substrate, and said insulation layer having
a trench groove;
a barrier metal layer on a bottom and side walls of said trench groove; and

RECEIVED
SEP 17 2002
TECHNOLOGY CENTER 2800

Do not
enter
TU

9/30/02

See C17
B1

See C3
B2